

EQD400-ER8

400Gb/s QSFP-DD ER8 1310nm SMF 40km Optical Transceiver

PRODUCT FEATURES

- **QSFP-DD MSA compliant**
- **Compliant to IEEE 802.3bs 400GBASE-ER8**
- **Digital diagnostic monitoring support**
- **Hot pluggable 76 pin electrical interface**
- **8 LAN-WDM lanes MUX/DEMUX design**
- **53.125Gbit/s PAM4 Channel Electrical Serial Interface (400GAUI-8)**
- **Maximum power consumption 15.4W**
- **LC duplex connector**
- **Supports 425Gb/s bit rate**
- **Up to 40km transmission on single mode fiber**
- **Operating case temperature: 05 to 70℃**
- **Single 3.3V power supply**
- **RoHS 2.0 compliant**

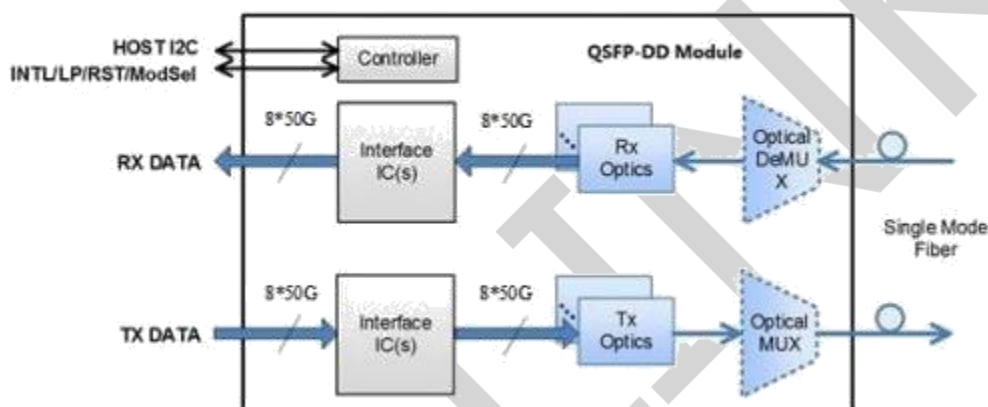
APPLICATIONS

- **400GBASE-ER8 Ethernet**
- **Telecom networking**
- **Data Center Interconnect**

DESCRIPTIONS

This module are designed for 40km optical communication applications, and it is compliant to IEEE 802.3bs for 400GE Ethernet. This module contains 8-lane optical transmitter, 8-lane optical receiver and module management block including 2 wire serial interface. The optical signals are multiplexed to a single- mode fiber through an industry standard LC connector.

Module Block Diagram



Ordering Information

Part No.	Data Rate(optical)	Laser	Fiber Type	Distance	Optical Interface	Temp	DDMI
EQD400-ER8	400Gb/s	EML	SMF	40km	LC	0~+70°C	Y

Absolute Maximum Ratings

It has to be noted that the operation in excess of any individual absolute maximum ratings might cause permanent damage to this module.

Parameter	Symbol	Min	Typ	Max	Units	Notes
Maximum Supply Voltage	Vcc	-0.5	3.3	3.6	V	
Storage Temperature	Ts	-40		85	□	
Relative Humidity	RH	10		85	%	1
Damage Threshold, each lane	THd	-3.4			dBm	

Notes : Non-condensing

Recommended Operating Conditions

Electrical and optical characteristics below are defined under this operating environment, unless otherwise specified.

Parameter	Symbol	Min	Typ	Max	Units
Supply Voltage	Vcc	3.135	3.3	3.465	V
Case Temperature	Top	0		70	°C
Link Distance with G.652				40	km

Electrical Characteristics

The following electrical characteristics are defined over the Recommended Operating Environment unless otherwise specified.

Parameter	Symbol	Min	Typical	Max	Units	Notes
Power Consumption				15.4	W	
Supply Current	Icc			4.444	A	Steady state
Transmitter (each Lane)						
Signaling Rate, each lane			26.5625		GBd	PAM4
Differential Voltage pk-pk	Vin, pp			880	mV	
Common Mode Voltage	Vcm	-0.3		2.8	V	
Common Mode Noise	RMS			17.5	mV	
Differential Termination Resistance Mismatch				10	%	
Transition time	Trise/Tfall	12			ps	20%~80%
Eye Width at 10 ⁻⁶ probability	EW6	0.2			UI	
Eye Height at 10 ⁻⁶ probability	EH6	32			mV	
Eye Linearity		0.85				
Receiver (each Lane)						
Signaling Rate, each lane			26.5625		GBd	PAM4
Differential Voltage pk-pk	Vout, pp			900	mV	

Transition time	Trise/Tfall	9.5			ps	20%~80%
Near-end eye width at 10-6probability	EW6	0.265			UI	
Near-end eye height at 10-6probability	EH6	70			mV	
Far-end eye width at 10-6probability	EW6	0.2			UI	
Far-end eye height at 10-6probability	EH6	30			mV	
Near-end Eye Linearity		0.85				

Notes:

1.400GAUI-8 Electrical Characteristics refers to CEI-56G-VSR-PAM4 of OIF-CEI-04.0

Optical and Characteristics

400GBASE-ER8 Operation (EOL, TOP = 0 to +70℃, VCC = 3.135 to 3.465 Volts)

Parameter	Min	Typical	Max	Units	Notes
Transmitter					
Signaling Speed per Lane	26.5625 ± 100 ppm			GBd	
Transmit wavelengths	1272.55	1273.54	1274.54	nm	
	1276.89	1277.89	1278.89	nm	
	1281.25	1282.26	1283.27	nm	
	1285.65	1286.66	1287.68	nm	
	1294.53	1295.56	1296.59	nm	
	1299.02	1300.05	1301.09	nm	
	1303.54	1304.58	1305.63	nm	
	1308.09	1309.14	1310.19	nm	
Total Average Launch Power			14.6	dBm	
Average launch power, each lane	-0.6		5.6	dBm	
Optical Modulation Amplitude (OMA), each lane	2.4		6.4	dBm	
Extinction Ratio (ER)	6			dB	
Side-Mode Suppression Ratio (SMSR)	30			dB	
Transmitter and Dispersion Eye Closure for PAM4 (TDECQ), each lane			3.4	dB	
Average launch power of OFF transmitter, each lane (max)			-30	dBm	
RIN15OMA			-132	dB/Hz	
Optical return loss tolerance			15	dB	

Transmitter reflectance			-26	dB	
Receiver					
Signaling Speed per Lane	26.5625 ± 100 ppm			GBd	
Transmit wavelengths	1272.55	1273.54	1274.54	nm	
	1276.89	1277.89	1278.89	nm	
	1281.25	1282.26	1283.27	nm	
	1285.65	1286.66	1287.68	nm	
	1294.53	1295.56	1296.59	nm	
	1299.02	1300.05	1301.09	nm	
	1303.54	1304.58	1305.63	nm	
	1308.09	1309.14	1310.19	nm	
Average receiver power, each lane	-18.6		-4.4	dBm	
Receiver power, each lane (OMA)			-3.6	dBm	
Difference in receive power between any two lanes(OMA)			5.8	dB	
Receiver sensitivity (OMA), each lane			RS	dBm	1
LOS Assert	-30			dBm	
LOS Deassert			-20.6	dBm	
LOS Hysteresis	0.5			dB	
Receiver reflectance			-26	dB	

Notes:RS=max(-16.1, SECQ-17.5) (dBm). For the requirement of receiver sensitivity, the value of BER is 2e-4 before FEC.

Digital Diagnostics

OM9660ES100 support the I2C-based Diagnostic Monitoring Interface (DMI) defined in document QSFP-DD Common Management Interface

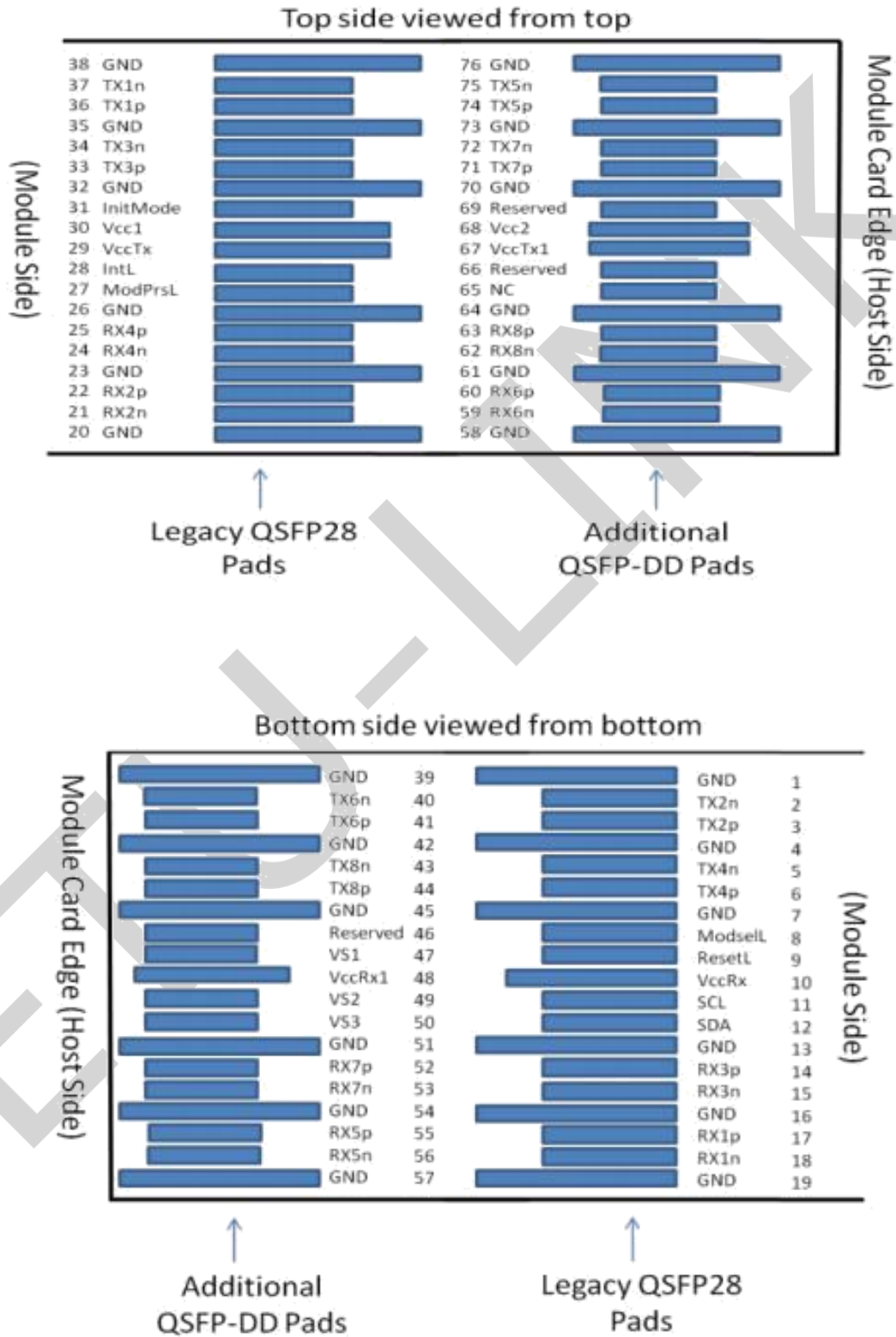
Specification Rev 4.0. The host can access real-time performance of transmitter and receiver optical power, temperature, supply voltage and bias current.

Performance Item	Related Bytes	Monitor Error	Notes
Module temperature	14 to 15 at Page low	+/-3°C	1 , 2
Module voltage	16 to 17 at Page low	< 5%	2
LD Bias current	170 to 185 at Page 11h	< 10%	2
Transmitter optical power	154 to 169 at Page 11h	< 3dB	2
Receiver optical power	186 to 201 at Page 11h	< 3dB	2

Notes:

1. Actual temperature test point is fixed on module case around Laser Array.
2. Full operating temperature range

Pin Diagram



Pin Definitions

PIN	Symbol	Name/Description	Notes
1	GND	Ground	1
2	Tx2n	Transmitter Inverted Data Input	
3	Tx2p	Transmitter Non-Inverted Data Input	
4	GND	Ground	1
5	Tx4n	Transmitter Inverted Data Input	
6	Tx4p	Transmitter Non-Inverted Data Input	
7	GND	Ground	1
8	ModSelL	Module Select	
9	ResetL	Module Reset	
10	VccRx	+3.3V Power Supply Receiver	2
11	SCL	2-wire serial interface clock	
12	SDA	2-wire serial interface data	
13	GND	Ground	1
14	Rx3p	Receiver Non-Inverted Data Output	
15	Rx3n	Receiver Inverted Data Output	
16	GND	Ground	1
17	Rx1p	Receiver Non-Inverted Data Output	
18	Rx1n	Receiver Inverted Data Output	
19	GND	Ground	1
20	GND	Ground	1
21	Rx2n	Receiver Inverted Data Output	
22	Rx2p	Receiver Non-Inverted Data Output	
23	GND	Ground	1
24	Rx4n	Receiver Inverted Data Output	
25	Rx4p	Receiver Non-Inverted Data Output	
26	GND	Ground	1
27	ModPrsL	Module Present	
28	IntL	Interrupt	
29	VccTx	+3.3V Power supply transmitter	2

30	Vcc1	+3.3V Power supply	2
31	LPMODE	Low Power mode	
32	GND	Ground	1
33	Tx3p	Transmitter Non-Inverted Data Input	
34	Tx3n	Transmitter Inverted Data Input	
35	GND	Ground	1
36	Tx1p	Transmitter Non-Inverted Data Input	
37	Tx1n	Transmitter Inverted Data Input	
38	GND	Ground	1
39	GND	Ground	1
40	Tx6n	Transmitter Inverted Data Input	
41	Tx6p	Transmitter Non-Inverted Data Input	
42	GND	Ground	1
43	Tx8n	Transmitter Inverted Data Input	
44	Tx8p	Transmitter Non-Inverted Data Input	
45	GND	Ground	1
46	Reserved	For future use	3
47	VS1	Module Vendor Specific 1	3
48	VccRx1	3.3V Power Supply	2
49	VS2	Module Vendor Specific 2	3
50	VS3	Module Vendor Specific 3	3
51	GND	Ground	1
52	Rx7p	Receiver Non-Inverted Data Output	
53	Rx7n	Receiver Inverted Data Output	
54	GND	Ground	1
55	Rx5p	Receiver Non-Inverted Data Output	
56	Rx5n	Receiver Inverted Data Output	
57	GND	Ground	1
58	GND	Ground	1
59	Rx6n	Receiver Inverted Data Output	
60	Rx6p	Receiver Non-Inverted Data Output	
61	GND	Ground	1

62	Rx8n	Receiver Inverted Data Output	
63	Rx8p	Receiver Non-Inverted Data Output	
64	GND	Ground	1
65	NC	No Connect	3
66	Reserved	For future use	3
67	VccTx1	3.3V Power Supply	2
68	Vcc2	3.3V Power Supply	2
69	ePPS	Precision Time Protocol (PTP) reference clock input. It is not used.	3
70	GND	Ground	1
71	Tx7p	Transmitter Non-Inverted Data Input	
72	Tx7n	Transmitter Inverted Data Input	
73	GND	Ground	1
74	Tx5p	Transmitter Non-Inverted Data Input	
75	Tx5n	Transmitter Inverted Data Input	
76	GND	Ground	1

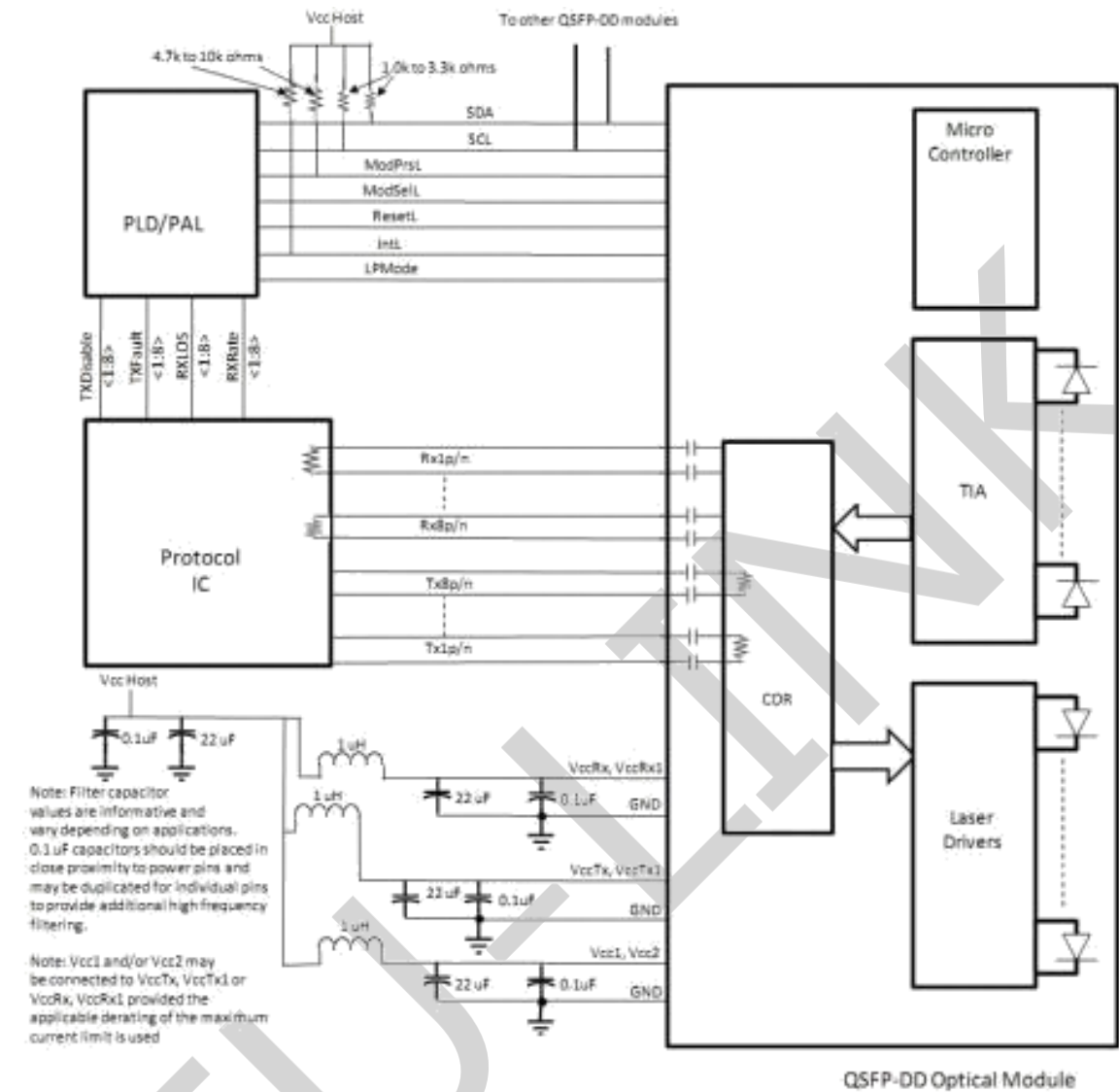
Notes:

1.QSFP-DD uses common ground (GND) for all signals and supply (power). All are comon within the QSFP-DD module and all module voltages are referenced to this po-te-nial unless otherwise noted. Connect these directly to the host board signal-common ground plane.

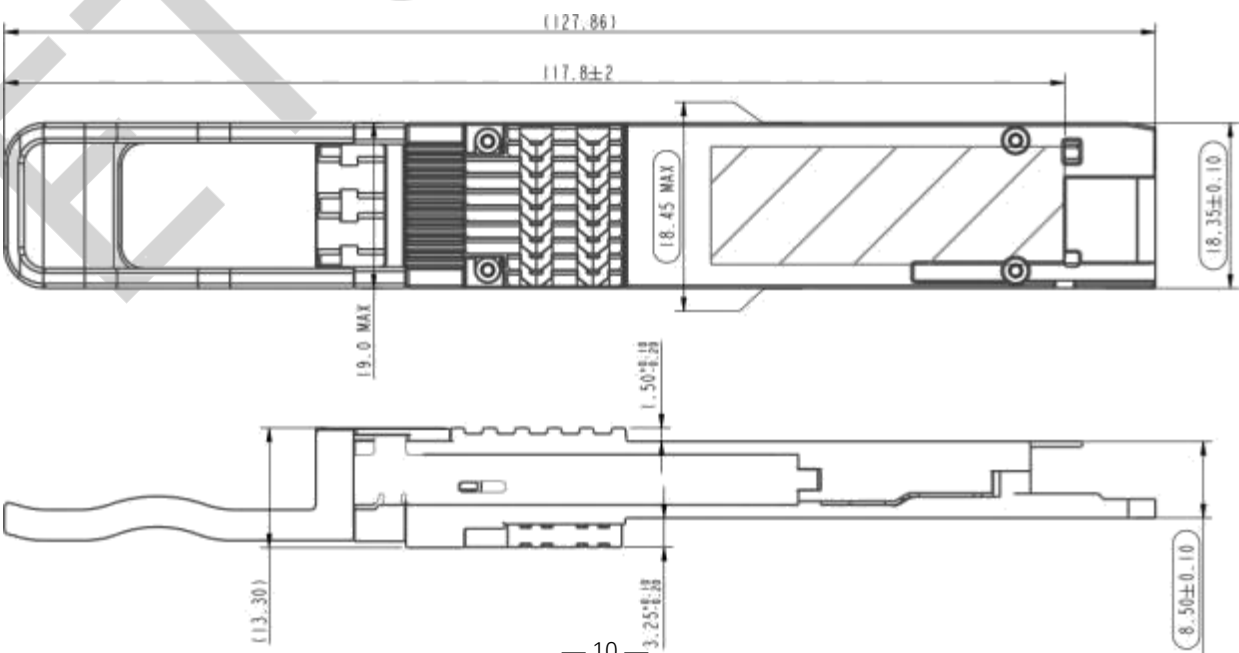
2.VccRx, VccRx1, Vcc1, Vcc2, VccTx and VccTx1 shall be applied concurrently.Requirements defined for the host side of the Host Card Edge Connector. VccRx, VccRx1, Vcc1, Vcc2, VccTx and VccTx1 may be internally connected within the module in any combination. The connector Vcc pins are each rated for a maximum current of 1000 mA.

3.All Vendor Specific, Reserved and No Connect pins may be terminated with 50ohms to ground on the host. Pad 65 (No Connect) shall be left unconnected within the module. Vendor specific and Reserved pads shall have an impedance to GND that is greater than 10K ohms and less than 100pF.

Recommended Interface Circuit



Mechanical Diagram



Revision History

Version No.	Date	Description
1.0	Aug 24, 2023	Preliminary datasheet
2.0	July 13,2024	Format change

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